

Title (en)  
High vacuum apparatus member and vacuum apparatus

Title (de)  
Hochvakuumanlage

Title (fr)  
Appareil à vide élevée

Publication  
**EP 0688879 A1 19951227 (EN)**

Application  
**EP 95107446 A 19950517**

Priority  
JP 16059694 A 19940620

Abstract (en)  
A material suitable for vacuum apparatuses which is easily dehydrogenated by baking. The material has a composition of high-purity oxygen-free copper with a purity of 99.99 wt% or greater, which contains prior to baking 1 to 15 ppm of Zr and 3 ppm or less of oxygen. <IMAGE>

IPC 1-7  
**C22C 9/00**

IPC 8 full level  
**C22C 9/00** (2006.01)

CPC (source: EP)  
**C22C 9/00** (2013.01)

Citation (search report)

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